



IEEE MTT-S International Conference on Microwave Acoustics & Mechanics

May 13-15, 2024, Chengdu, China

Conference General Chair chairs.icmam@mtt.org

Ken-ya Hashimoto
University of Electronic Science
and Technology of China, China

Technical Program Chairs

Shuji Tanaka
Tohoku University, Japan
Amelie Hagelauer
Technical University of Munich,
Fraunhofer EMFT, Germany

Conference Finance Chairs finance.icmam@mtt.org

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Call for Papers

The International Conference on Microwave Acoustics & Mechanics (IC-MAM) represents a unique and unprecedented opportunity to bring together researchers and practitioners of different backgrounds (materials scientists, physicists, microwave engineers and process technologists), to share the most recent advances in new materials and manufacturing processes as well as components and devices, which represent the key for the development of future RF, microwave, mm-wave and THz devices, circuits, and systems based on RF-MEMS and Acoustics. IC-MAM is organized by the IEEE Microwave Theory and Technology Society (MTT-S) and features an exciting technical program and invited talks by worldwide- recognized experts of RF-MEMS and BAW/SAW

Conference Topics

Perspective authors are cordially invited to submit papers in all areas of Microwave Acoustics and RF MEMS including but not limited to:

- Acoustic/MEMS Device Applications
- Acoustic/MEMS Device Design
- Acoustic/MEMS Device Modeling
- Materials & Propagation
- Advances in Filter and Multiplexer Technology
- SAW and BAW Sensor Devices and Applications
- Multi-Band RF Modules for Multi-Standard/-Mode Systems
- Fusion of Major Transmit and Receive Functionality in Single Modules
- Tunable & Reconfigurable Devices, like Bulk and Thin-film Components and Devices, e.g., based on Ferroelectrics, Phase-Change Materials

Submitted papers should be three to four pages in length. Authors must adhere to the format of the IEEE conference paper template. Papers submitted will be peer-reviewed and all papers presented at the conference will be included in IEEE Xplore pending quality review.

Submission deadline:	February 18, 2024
Notification of acceptance:	March 16, 2024
Final paper submission:	April 13, 2024
Conference date:	May 13 - 15, 2024

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